



## Final Product Change Notification

202112006F02 : Additional Wafer Source for SE05x, A5000 and Related Products

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### Management summary

NXP is making an additional wafer foundry available for the CMOS040 technology used to manufacture wafers for SE05x products, as well as J3R and A5000 products. For orders after the change, NXP planners can source material from one of two possible foundries. The commercial type naming scheme is adapted to make this dual-sourcing possible without changes to existing customer ordering type names or 12NCs (ordering codes).

### Change Category

- Wafer Fab Process
- Assembly Process
- Product Marking
- Test Process
- Design
- Wafer Fab Materials
- Assembly Materials
- Mechanical Specification
- Test Equipment
- Errata
- Wafer Fab Location
- Assembly Location
- Packing/Shipping/Labeling
- Test Location
- Electrical spec./Test coverage
- Firmware
- Other

## PCN Overview

### Description

Besides the existing source for wafers, a second source will become available after the change. This is Globalfoundries fab 1 in Dresden, Germany (GF1). This foundry will produce products with the same form, fit and function as the existing source (Globalfoundries fab 7 in Singapore, GF7). GF1 has the same quality and security certifications like GF7. NXP has performed an extensive qualification process to ensure wafer supplies are equivalent from both sources in all observable aspects.

To help our customers execute future orders in a more flexible way, the type naming scheme for affected parts is changing. There is a change in the coding for the letter that identifies wafer source. The letter "z", which previously had the meaning "wafer source GF7" will have the meaning "wafer source GF1 or GF7" after the change. Individual customer orders will typically be fulfilled only from one single source each, not from a mixture of both sources.

### Reason

NXP strives to provide larger flexibility to customers and our production fulfilment. Being able to source wafers for EdgeLock SE05x, J3R and A5000 products from more than one source will provide a more resilient supply situation. In the light of the global semiconductor supply broadly discussed in public media, we believe this change will be helpful.

#### **Identification of Affected Products**

Product identification does not change

#### **Product Availability**

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#### **Sample Information**

Samples are available from Oct 03, 2022

#### **Production**

Planned first shipment Oct 17, 2022

#### **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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No Impact on form, fit, function, reliability or quality

#### **Data Sheet Revision**

No impact to existing datasheet

#### **Disposition of Old Products**

"old products" does not apply, as GF7 will still remain a valid wafer production source also after the change.

#### **Additional information**

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Self qualification: [view online](#)

#### **Timing and Logistics**

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Nov 01, 2022.

#### **Contact and Support**

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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